PATENT ASSIGNMENT COVER SHEET

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SUBMISSION TYPE:	NEW ASSIGNMENT
NATURE OF CONVEYANCE:	ASSIGNMENT

CONVEYING PARTY DATA

Name	Execution Date	
Hiroaki NITTA	03/03/2015	
Hideyuki AKANUMA	03/04/2015	
Kazunobu KUWAZAWA	03/06/2015	

RECEIVING PARTY DATA

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PROPERTY NUMBERS Total: 1

Property Type	Number	
Application Number:	14669714	

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Correspondence will be sent to the e-mail address first; if that is unsuccessful, it will be sent using a fax number, if provided; if that is unsuccessful, it will be sent via US Mail.

using a fax number, if provided; if that is unsuccessful, it will be sent via US Mail.

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ATTORNEY DOCKET NUMBER: 165679

NAME OF SUBMITTER: ANGELA M. NOLAN

SIGNATURE: /Angela M. Nolan/

DATE SIGNED: 03/26/2015

Total Attachments: 2

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PATENT 503237608 REEL: 035265 FRAME: 0773

譲渡証 (Translation/日本語訳)

下記に署名した私/私達、

新田 博明,赤沼 英幸,桑沢 和伸,

は、ある発明を創出し、これについて合衆国特許出願は

\boxtimes	ここに私/私達	により署名	され,
	に私/私	達により(そ	れぞれ)署名され
	に出願され、	出願番号	が交付され、
	PCT 国際出願	として	に出願され、
7	の発明は、		,

半導体装置及びその製造方法

という名称である。 そして、ここにその受領を認める対価で:私/私達は、当該発明/出願について、合衆国とその属領及び全ての外国に於ける全面的かつ独占的な権利;合衆国とその属領及び全ての外国に於いて発行される特許証に関わる全ての権利、所有権、利益; 一部継続出願、継続出願、分割出願、差替之出願、再発行出願、特許期間延長等、合衆国とその属領及び全ての外国に於いて既に出願されたか若しくは今後出願される特許に関わる全ての権利;そして、国際条約、同盟、契約、法令、協定(将来制定されるものを含む)に基づく全ての優先権を伴う一切の権利;を、日本国東京都新宿区西新宿二丁目1番1号に住所を有するセイコーエプソン株式会社、その後継者、譲受人及び法定代理人に対して、売却、譲渡、移転するものとする。

さらに、私/私達は、セイコーエプソン株式会社、(以下譲受人 と言う) が単数ないしは複数の当該発明(以下当該発明という) に関わる特許権を、自己の名により、合衆国とその属領及び全 ての外国に於いて出願し、特許を受けること;またこの譲渡証 の意図と目的を誠実に実行することを求められた場合、下記に 署名した私/私達が、当該譲受人、その後継者、その被譲渡者、 及び法定代理人の費用負担にて、一部継続出願、継続出願、分 割出願、差替え出願、再発行出願、特許期間延長等を行い、合 法的宣誓書、譲渡証、委任状等の書類を作成し、あらゆる法的 または準法的訴訟手続に於いて証言を行うこと;当該発明とそ の経緯に関連して、下記に署名した私/私達が知り得た全ての 事実を、当該譲受人、後継者、被譲渡者、及び法定代理人に連 絡すること;そして当該譲受人、後継者、被譲渡者、及び法定 代理人が、当該発明の特許権の適切な保護、維持、権利行使す るために望ましいと考慮すること、また、当該発明に関わる特 許出願に際し、当該譲受人、後継者、被譲渡者、及び法定代理 人に対して法的権限を付与することが望ましいと考慮すること について、可能な限り行うことを承諾する。

Assignment

For good and valuable consideration, the receipt of which is hereby acknowledged, I/WE, the undersigned,

Hiroaki NITTA , Hideyuki AKANUMA , Kazunobu KUWAZAWA ,

who have created a certain invention for which an application for United States Letters Patent

\boxtimes	executed by ME/US on even date herewith,			
	executed by ME/US on , (respectively),			
	filed on and assigned Serial No.			
	filed as International Application No. filed or	n		
and	nd entitled:			
SEM	MICONDUCTOR DEVICE AND MANUFACTURIN	۱G	METH	OD
FOR	R THE SAME			

Do hereby sell, assign and transfer to SEIKO EPSON CORPORATION, having a place of business 4-1, Nishi-shinjuku 2-chome, Shinjuku-ku, Tokyo 163-0811 Japan its successors, assigns, and legal representatives, the full and exclusive right to said invention and said application and to any and all inventions described in said application for the United States, its territorial possessions and all foreign countries, and the entire right, title and interest in and to any and all Letters Patent which may be granted therefor in the United States, its territorial possessions and all foreign countries; and in and to any and all continuations-in-part, continuations, divisions, substitutes, reissues, extensions thereof, and all other applications for Letters Patent relating thereto which have been or shall be filed in the United States, its territorial possessions and/or any foreign countries, and all rights, together with all priority rights, under any of the international conventions, unions, agreements, acts, and treaties, including all future conventions, unions, agreements, acts, and treaties;

Agree that SEIKO EPSON CORPORATION hereinafter referred to as Assignee, may apply for and receive Letters Patent for said invention and said inventions, hereinafter referred to as said invention, in its own name, in the United States, its territorial possessions, and all foreign countries; and that, when requested to carry out in good faith the intent and purpose of this assignment, at the expense of said Assignee, its successors, assigns and legal representatives, the undersigned will execute continuations-in-part, continuations, divisions, substitutes, reissues, extensions thereof, execute all rightful oaths, assignments, powers of attorney and other papers, testify in any legal or quasi legal proceedings; communicate to said Assignee, its successors, assigns or legal representatives all facts known to the undersigned relating to said invention and the history thereof; and generally do everything possible which said Assignee, its successors, assigns, or legal representatives shall consider desirable for aiding in securing, maintaining and enforcing proper patent protection for said invention and for vesting title to said invention and all applications for patents on said invention in said Assignee, its successors, assigns, or legal representatives; and

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そして、私/私達は、この書面により譲渡された権利や財産に影響する、如何なる譲渡、授権、抵当権、ライセンス等その他の協定も他の第三者との間で行っていないこと; 下記に署名した私/私達によって、この書面に記載されている権利が所有されていることを、当該譲受人、後継者、被譲渡者、及び法定代理人に対して誓約するものである。

さらに、下記に署名した私/私達はこの譲渡書は英語の部分の表現によってのみ解釈されることに同意する。

上記を証明するため、私/私達は下記日付で署名する。

Covenant with said Assignee, its successors, assigns, or legal representatives that no assignment, grant, mortgage, license or other agreement affecting the rights and property herein conveyed has been made to others by the undersigned, and that full right to convey the same as herein expressed is possessed by the undersigned.

I/WE, the undersigned do further agree that this Assignment is to be construed solely according to the terms of the English language portions thereof.

IN TESTIMONY WHEREOF I/WE have hereunto set MY/OUR signature seal on the date indicated below.

日付	Hiroaki NITTA Inventor's signature	Date
	_	Date.
	(: 1 \ d / .	
2015年3月3日	Hiroahi Mitta	March 3, 2015
	Legal name of Second joint inventor, if	any
	Hideyuki AKANUMA	
日付	•	Date
2015年3月4日	Hideyuki Akanuma	March 4,2015
	Legal name of Third joint inventor, if an	у
	Kazunobu KUWAZAWA	
日付	Third Inventor's signature	Date
2015年3月6日	Kazunobi Kiwazawa	March 6,2015
	Legal name of Fourth joint inventor, if a	ny
日付	Fourth Inventor's signature	Date
	Legal name of Fifth joint inventor, if any	,
日付	Fifth Inventor's signature	Date
	Legal name of Sixth joint inventor, if any	y
日付	Sixth Inventor's signature	Date
	Legal name of Seventh joint inventor, if	any
日付	Seventh Inventor's signature	Date
	Legal name of Eighth joint inventor, if ar	у
日付	Eighth Inventor's signature	Date
	日付 2015年3月45日 日付 日付	日付 Second Inventor's signature 2015年3月4日 日は とりは、Akanumの Legal name of Third joint inventor, if an Kazunobu KUWAZAWA 日付 Third Inventor's signature 2015年3月6日 とないのとしとないでは、 Legal name of Fourth joint inventor, if an Fourth Inventor's signature Legal name of Fifth joint inventor, if any 目付 Fifth Inventor's signature Legal name of Sixth joint inventor, if any 目付 Sixth Inventor's signature Legal name of Seventh joint inventor, if any 日付 Seventh Inventor's signature Legal name of Seventh joint inventor, if any Legal name of Seventh joint inventor, if Seventh Inventor's signature

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